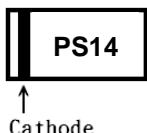


RoHS Compliant Product
A suffix of "C" specifies halogen-free and RoHS Compliant

FEATURES

- Heatsink Structure
- Low Profile, Typical Thickness 0.8mm
- Moisture Sensitivity: Level 1, Per J-STD-020
- High Temperature Soldering Guaranteed: 260°C/10 Seconds

MARKING



PACKAGE INFORMATION

Package	MPQ	Leader Size
SOD-123DT	3K	7 inch

ORDER INFORMATION

Part Number	Type
SM120DT~SM140DT	Lead (Pb)-free
SM120DT-C~SM140DT-C	Lead (Pb)-free and Halogen-free

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Part Number			Unit	
		SM120DT	SM130DT	SM140DT		
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	30	40	V	
Maximum RMS Voltage	V_{RMS}	14	21	28	V	
Maximum DC Blocking Voltage	V_{DC}	20	30	40	V	
Minimum Breakdown Voltage @ $I_R=1\text{mA}$	V_{BR}	20	30	40	V	
Maximum Average Forward Rectified Current	I_F	1			A	
Peak Forward Surge Current@ 8.3 ms Single Half Sine-Wave Superimposed on Rate Load	I_{FSM}	30			A	
Rating for Fusing ($t<8.3\text{ms}$)	I^2t	4			A^2s	
Maximum Instantaneous Forward Voltage $I_F=1\text{A}, T_A=25^\circ\text{C}$	V_F	0.5			V	
		0.5				
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_A=25^\circ\text{C}$	I_R	50			μA	
		1				
Typical Junction Capacitance	C_J	51.2			pF	
Typical Thermal Resistance from Junction to Ambient ¹	$R_{\theta JA}$	65			$^\circ\text{C/W}$	
Typical Thermal Resistance from Junction to Case ²	$R_{\theta JC}$	35				
Typical Thermal Resistance from Junction to Lead ¹	$R_{\theta JL}$	9				
Operating Junction and Storage Temperature	T_J, T_{STG}	-55~150			$^\circ\text{C}$	

Notes:

1. The thermal resistance from junction to ambient or lead, mounted on P.C.B with 5x5mm copper pads, 2 OZ, FR4 PCB.
2. The thermal resistance from junction to case, mounted on P.C.B with recommended copper pads, 2 OZ, FR4 PCB.

CHARACTERISTIC CURVES

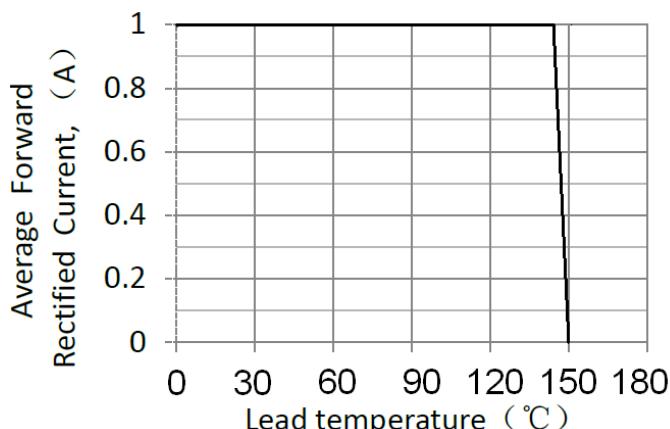


Figure 1. Forward Current Derating Curve

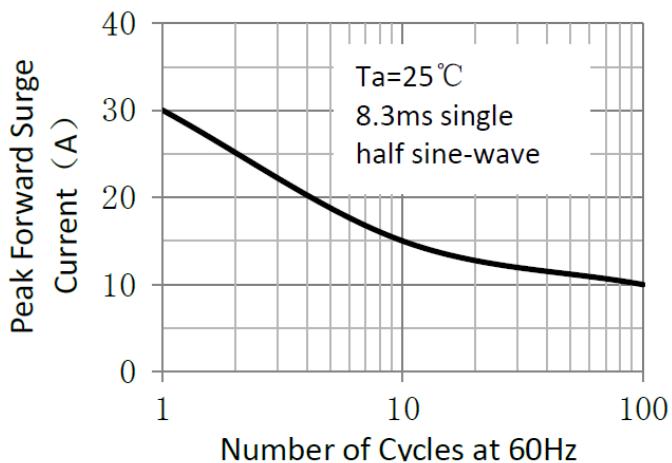


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

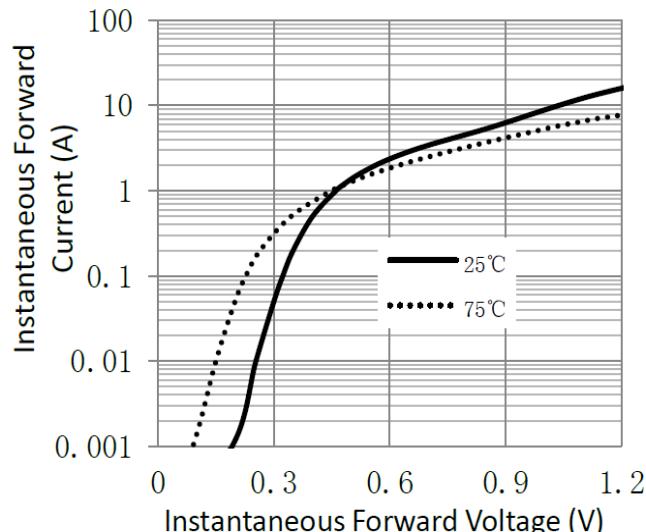


Figure 3. Typical Instantaneous Forward Characteristics

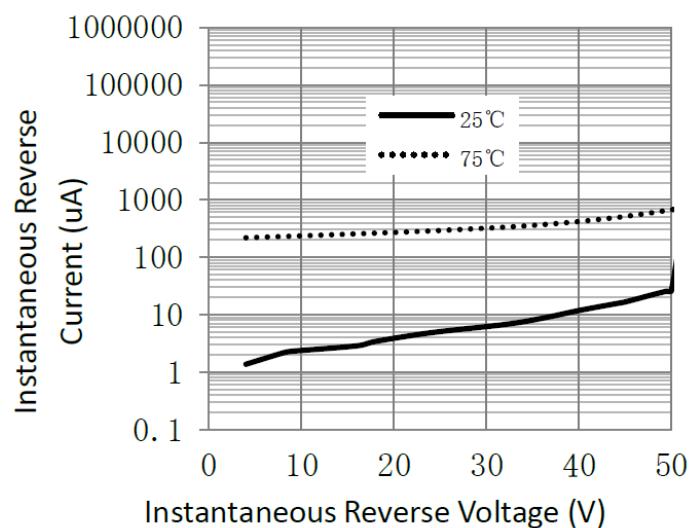


Figure 4. Typical Reverse Characteristics

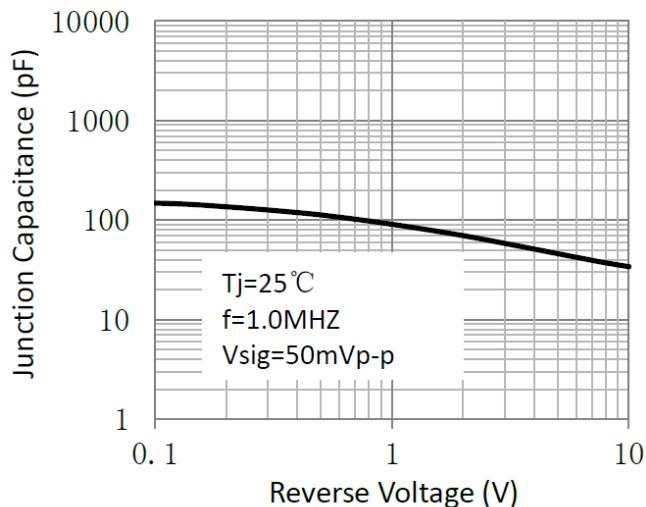


Figure 5. Typical Junction Capacitance